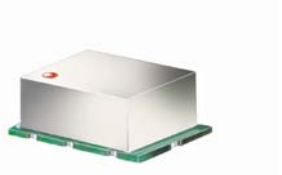
Engineering Development Model

Bi-Directional Coupler SYDC-ED13563/1

Important Note

This model has been designed, built and tested in our engineering department. Performance data represents model capability.
At present it is a non-catalog model. On request, we can supply a final specification sheet, part number and price/delivery information.

Please click "Back", and then click "Contact Us" for Applications support.



CASE STYLE : AH202-1

ELECTRICAL SPECIFICATIONS 50Ω @ +25°C					
Parameter		**Min.**	**Typ.**	**Max.**	**Units**
Frequency		3		120	MHz
Coupling	**Nominal**		29±1.5		dB
	Flatness		±.80		dB
Mainline Loss*	**3-30 MHz**		0.02		dB
	30-60 MHz		0.04		dB
	60-120 MHz		0.06		dB
Directivity	**3-30 MHZ**		26		dB
	30-60 MHz		32		dB
	60-120 MHz		27		dB
VSWR	**3-120 MHz**		1.03		(:1)
RF Power Input (1)	**3-120 MHz**			55	W

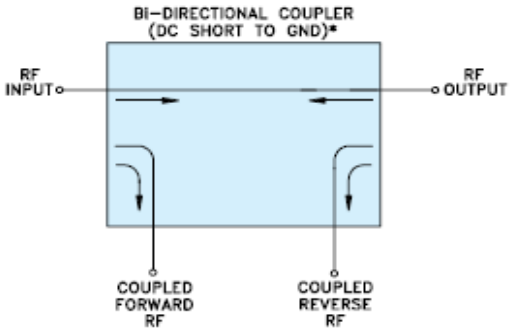
(1) The user must provide adequate means of heat removal to limit the temperature of ground connections 2,3,6,7 to 85°C, in order to ensure proper performance. At 25°C ambient temperature this requires thermal resistance of the user's PC board heat sink to be 35°C/W or less when the unit is driven at maximum specified RF input power, 55W. At higher ambient temperature, with the same heat sink, input power in watts must not exceed 55W x (85°C -Tambient) ÷ 60°C.

Note: * Mainline loss includes theoretical coupled power loss of .005 dB at 29 dB coupling.

MAXIMUM RATINGS	
Operating Temperature	-40°C to +85°C
Storage Temperature	-55°C to 100°C

PIN CONNECTIONS	
INPUT	8
OUTPUT	1
COUPLED FORWARD	5
COUPLED REVERSE	4
GROUND	2,3,6,7

Electrical Schematic



* ELECTRICAL SCHEMATIC IS FOR BI–DIRECTIONAL COUPLER WITH INTERNAL TRANSFORMER(S) THAT ROUTES DC FROM RF PORTS TO GROUND.